



AMD EPYC™ “MILAN” UPDATE

3RD GEN EPYC 7000 PROCESSORS

MICHAEL OSTER

SERVER PARTNER BUSINESS MANAGER- GERMANY

DATA CENTER GROWTH

DELIVERING leadership compute and graphics DIFFERENTIATION



SUPERCOMPUTING

Leading the Exascale Era

Consistently Winning Top Deployments

SDSC
SAN DIEGO SUPERCOMPUTER CENTER

ECMWF

HLRI
High Performance Research Institute

INDIANA UNIVERSITY

Microsoft Azure



Google



CLOUD

Expanding Deployments
with Top 10 Providers

Doubled in 2019

150+ INSTANCES

Expected in 2021*



ENTERPRISE

Large-scale Enterprise Deployments
with Growing Pipeline

Doubled in 2019

150+ PLATFORMS

Expected in 2021*

AMD EPYC™ MOMENTUM EVERYWHERE

Powering the Exascale Era

4.5x-9x faster than today's top supercomputers



High Performance Compute



Design & Simulation



Research & Academia



Machine Learning



Supercomputing

Powering the Cloud

9 of 10 most powerful Cloud Providers in the World



Cloud Service Providers



IaaS/PaaS



Search



Social



SaaS

Powering the Enterprise

Performance and Security Leadership in the workloads that matter



Enterprise IT



Virtualization



SDS/HCI

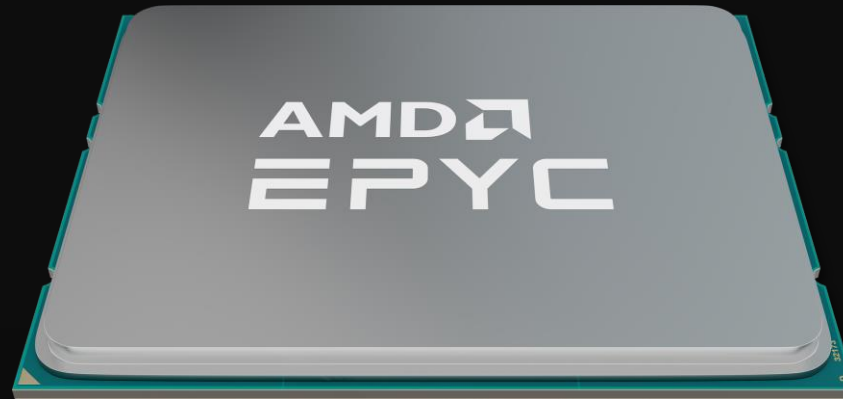


Hadoop



NoSQL

ADVANCED SECURITY FEATURES WITH INFINITY GUARD™



3RD GEN AMD EPYC™

THE WORLD'S HIGHEST PERFORMANCE x86 SERVER PROCESSORS, PER-CORE AND THROUGHPUT

Designed to Power the Most
Important Cloud Services

Delivering the Best
Business Value

Providing the Assurance
of Modern Security

WHERE WE ARE TODAY



Predictable Execution



Leadership Performance

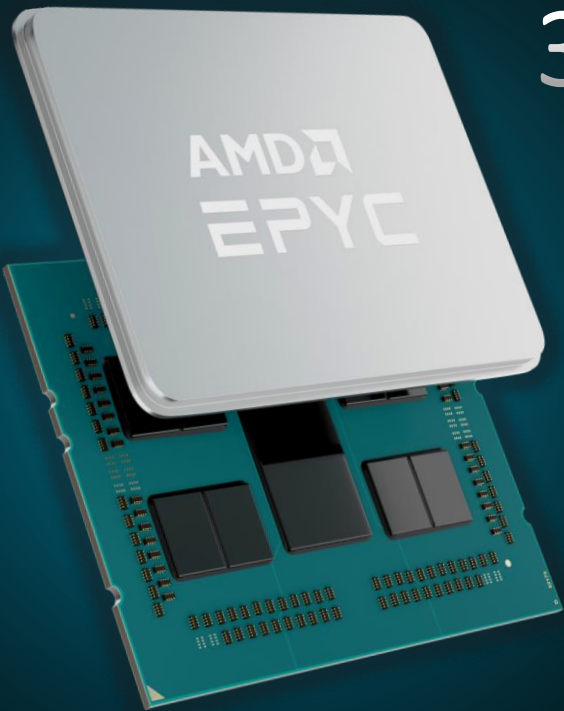


Strong Roadmap

AMD EPYC™ SERVER CPU NDA ROADMAP

Relentless Technology Innovation





3RD GEN EPYC™ “MILAN” CPU

UNDISPUTED LEADERSHIP PERFORMANCE

Up To

25%¹

More mid-stack performance
where customers are buying

Up to

15%¹

Better perf / \$ vs.
previous generation

Leading Throughput
Performance²

Per Core
Performance²

Best TCO Across
Workloads²

Leadership Security Features
(SME, SEV-ES, SEV-SNP)

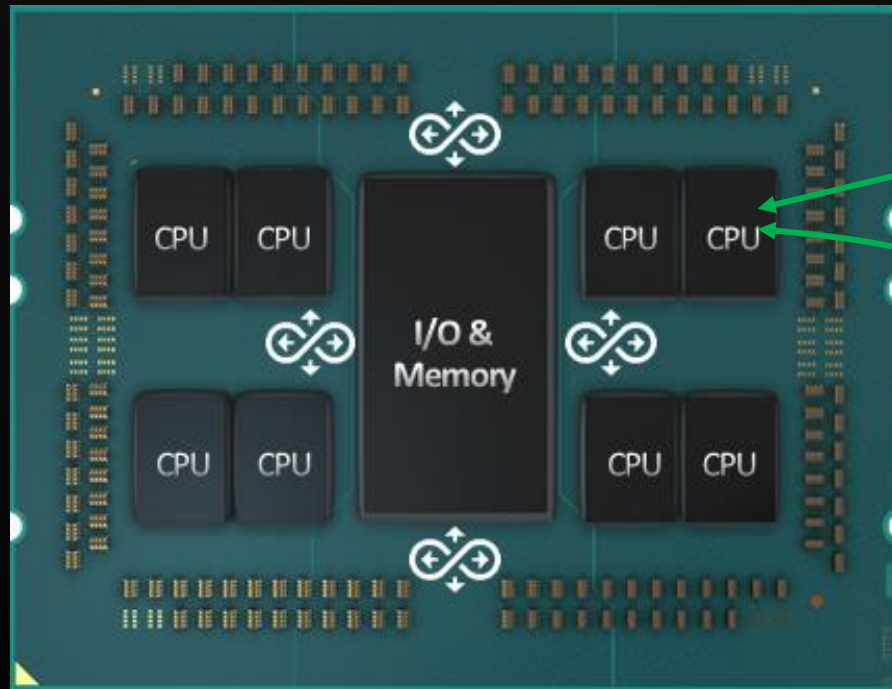
No Compromise
Single Socket

¹ Comparison based on est SPECrate@2017_int_base scores for servers with preproduction 32 core EPYC 7542 vs. preproduction 32 core EPYC 7543 processors. AMD prices 1kU Dec 2020. SPEC®, SPECrate® and SPEC CPU® are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information.

² Performance numbers based on AMD internal estimates. Subject to change based on actual results.

“MILAN” BUILDS ON INFINITY ARCHITECTURE

7002 (“ROME”) & “MILAN” 9 DIE MCM (8 CCD + 1 IO)



“Zen2”/7002 (“Rome”)

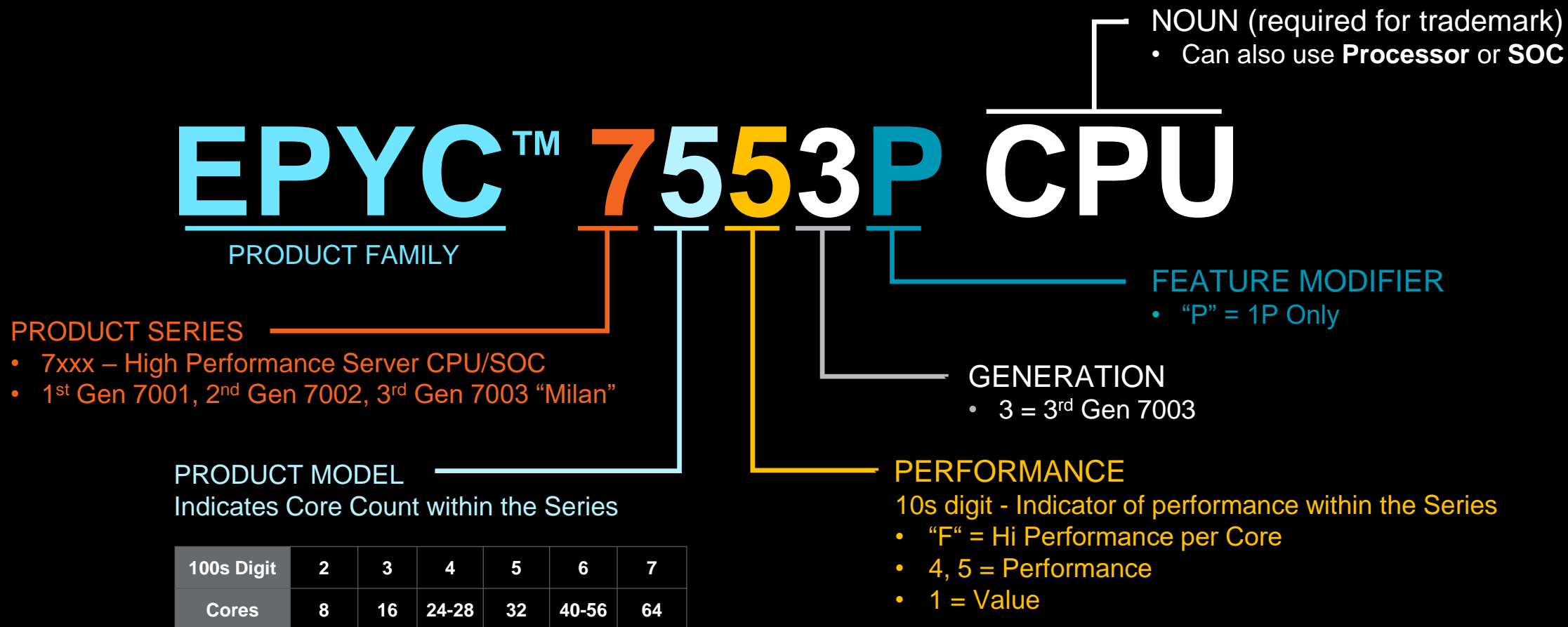
Z2	L2	16MB L3	L2	Z2
Z2	L2		L2	Z2
Z2	L2	16MB L3	L2	Z2
Z2	L2		L2	Z2

“Zen3”/“Milan”

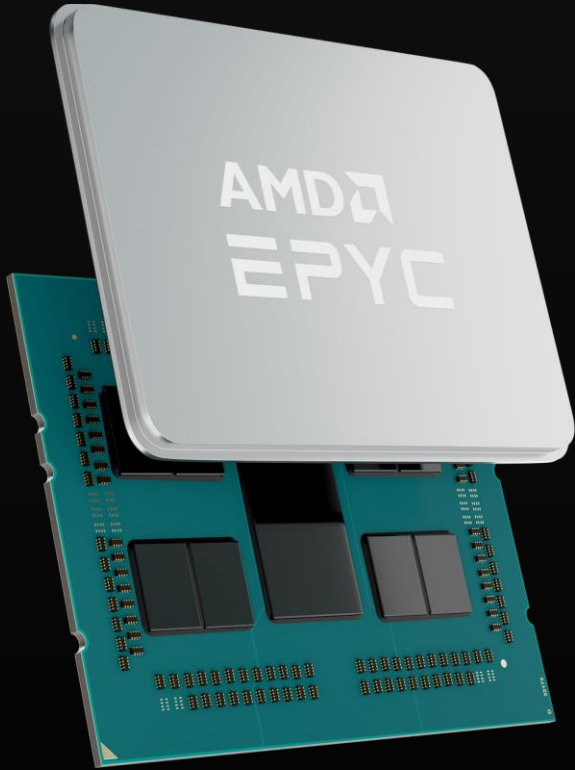
Z3	L2	32 MB L3	L2	Z3
Z3	L2		L2	Z3
Z3	L2		L2	Z3
Z3	L2		L2	Z3

AMD EPYC™ PROCESSOR NAMING CONVENTION

STARTING with EPYC 7003 Series - “MILAN”

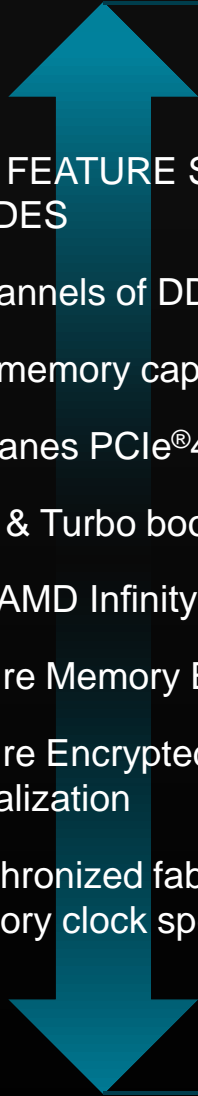


AMD EPYC™ 7003 CPU MODELS



ALL-IN FEATURE SET INCLUDES

- 8 Channels of DDR4-3200
- 4TB memory capacity
- 128 lanes PCIe®4
- SMT & Turbo boost
- 18G AMD Infinity Fabric™
- Secure Memory Encryption
- Secure Encrypted Virtualization
- Synchronized fabric and memory clock speeds



CORES	AMD EPYC	
	7763	
64 CORES	7713/P	
56 CORES	7663	
48 CORES	7643	
	75F3	"F" Performance Per Core Optimized
	7543/P	
32 CORES	7513	
28 CORES	7453	
	74F3	
	7443/P	
24 CORES	7413	
	73F3	
	7343	
16 CORES	7313/P	
8 CORES	72F3	

AMD EPYC™ 7003 “MILAN” SOFTWARE AND SOLUTIONS ECOSYSTEM

65+ ISVs / IHVs support at launch

<u>OS</u>	<u>IHV (Solution Engagements Only)</u>	<u>SDS</u>	<u>Big Data Analytics</u>	<u>Databases</u>	<u>HPC ISVs</u>	<u>HPC Open Source</u>	<u>Telco</u>
Canonical	Broadcom	RHEL Ceph	Apache Hadoop	MS SQL Server	Altair	Weather: WRF	Ericsson
Citrix	Mellanox	Excelro	Cloudera	MySQL	Ansys	Weather: HYCOM	Mavenir
Microsoft	Micron	Pivot 3	Couchbase	Oracle DB	Dassault Systems	Weather: IFS	Mellanox
Oracle	NVIDIA	Quobyte	DataStax	PostgreSQL	Emerson	NAMD	NetScout
Red Hat	Samsung	Weka.IO	Elastic	Redislabs	ESI	CP2K	Nokia
Suse	Kioxia*	Cloudian*	Exasol	SAP	LSTC	Open Foam	Red Hat
VMware	Marvell*	MapR-XD*	MongoDB	TigerGraph	Mentor Graphics	GROMACS	VMware
	Microchip*	StorMagic*	Splunk	Vertica	MSC	LIGGGHTS	Keysight (Ixia-BP)*
	SK Hynix*		Transwarp	MemSQL*	Shearwater	LAMMPS	Palo Alto Networks*
	Seagate*		Databricks*	Oracle EBS*	Siemens PLM		
	Western Digital*		Hortonworks*	SAP HANA*	Synopsys		
			MapR*	SAS*	Cadence*		
			MarkLogic*		Flow Science*		
			Splunk*		Haliburton*		
			Tableau*		Schlumberger*		
			Snowflake*				
<u>SDI</u>	<u>Accelerators</u>					<u>High Perf.</u>	<u>Media</u>
Microsoft	Pesando					Formulus Black*	Autodesk
Red Hat	Xilinx					Rescale*	BEAMR
VMware	nCorium*					ScaleMP*	ATEME*
							Blackmagic*
							Chaos Group*
							Foundry*
							Pixar*

* 30+ additional ISVs supported post launch



CHANGING THE ECONOMICS OF THE
VIRTUALIZED DATACENTER

Vielen Dank!

BACKUP

AMD EPYC™ CPUS

DELIVERING leadership compute and graphics DIFFERENTIATION



HPC

- CPU optimized for GPU acceleration
- Massive I/O for cluster connectivity
- Memory capacity for large datasets
- Massive I/O bandwidth for NVMe drives



HCI VIRTUALIZATION & VDI

- High core count to enable dense user base
- Large memory capacity enabling more VMs
- Secure Encrypted Virtualization (SEV)
- Massive I/O for scale-out environments
- Single-Socket enabling TCO advantages in socket-based licensed solutions



CLOUD

- High core count to meet SLAs
- Large memory capacity enabling more VMs
- Enabling Confidential Cloud Computing
- Massive I/O for scale-out environments



DATA ANALYTICS - Research & Academia

- High parallelism for complex analysis
- Massive I/O bandwidth for fast data loading
- High integer and floating-point capacity
- Additional security features for business critical data



DATA ANALYTICS - Machine Learning

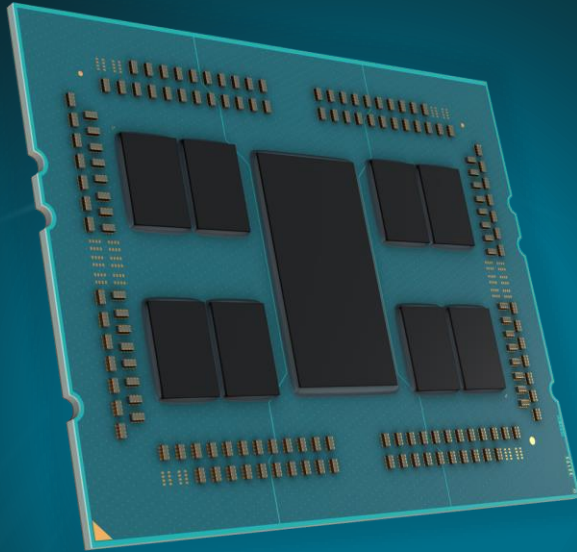
- Highly parallelized CPU optimized for GPU acceleration
- High parallelism for real time data streams
- High core count for inference
- Massive I/O bandwidth for NVMe™ drives



DATA ANALYTICS – ENTERPRISE IT

- Direct SATA & NVMe Support
- High parallelism for low latency
- More L3 Cache for fast data processing
- Full memory encryption helping improve data security

AMD EPYC™ 7003 PROCESSORS – “MILAN”



“Zen3” Core Delivering
Performance Enhancements

No New Hardware – Drop-in Compatible with Rome
Platforms (*BIOS update required*)

Enhanced Security Features

Supports 4, 6 or 8 Memory Channels Configs

Enhanced Memory Performance with:
Infinity Fabric™ and Memory Clock Synchronized
Largest Available x86 L3 Cache – Up to 32MB / core

WORLD'S HIGHEST PERFORMANCE
x86 CPU*

3RD GENERATION AMD EPYC™ LEADERSHIP ARCHITECTURE

AMD Infinity Architecture – The Foundation Of The Modern Data Center



EFFICIENCY ✓

Hybrid Multi-Die SoC Design

Optimized with CPU and Memory Clock Sync
Price / Performance / Watt Industry Leader*

PERFORMANCE ✓

Core Performance Upgrades

Up to 25% increase in mid-core CPUs*
Higher Frequencies for better performance



3RD GENERATION



INFINITY FABRIC™



SECURITY ✓

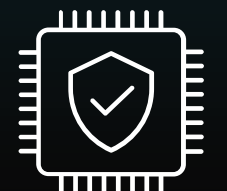
AMD Infinity Guard

Secure Nested Paging (SEV/SNP) added to
EPYC advanced security features

MEMORY ✓

Breakthrough System Features

First x86 CPU with up to 32MB L3 cache / Core
4, 6, and 8 Channel Memory Optimized



AMD EPYC™ 7003 “MILAN” - AT A GLANCE

COMPUTE

AMD “Zen3” x86 cores (up to 64 core / 128 threads)

Up to 32MB L3 cache / core, shared by each chiplet

Flatter NUMA domain, reduced latency w/ smaller system diameter

TDP range: 120W-280W

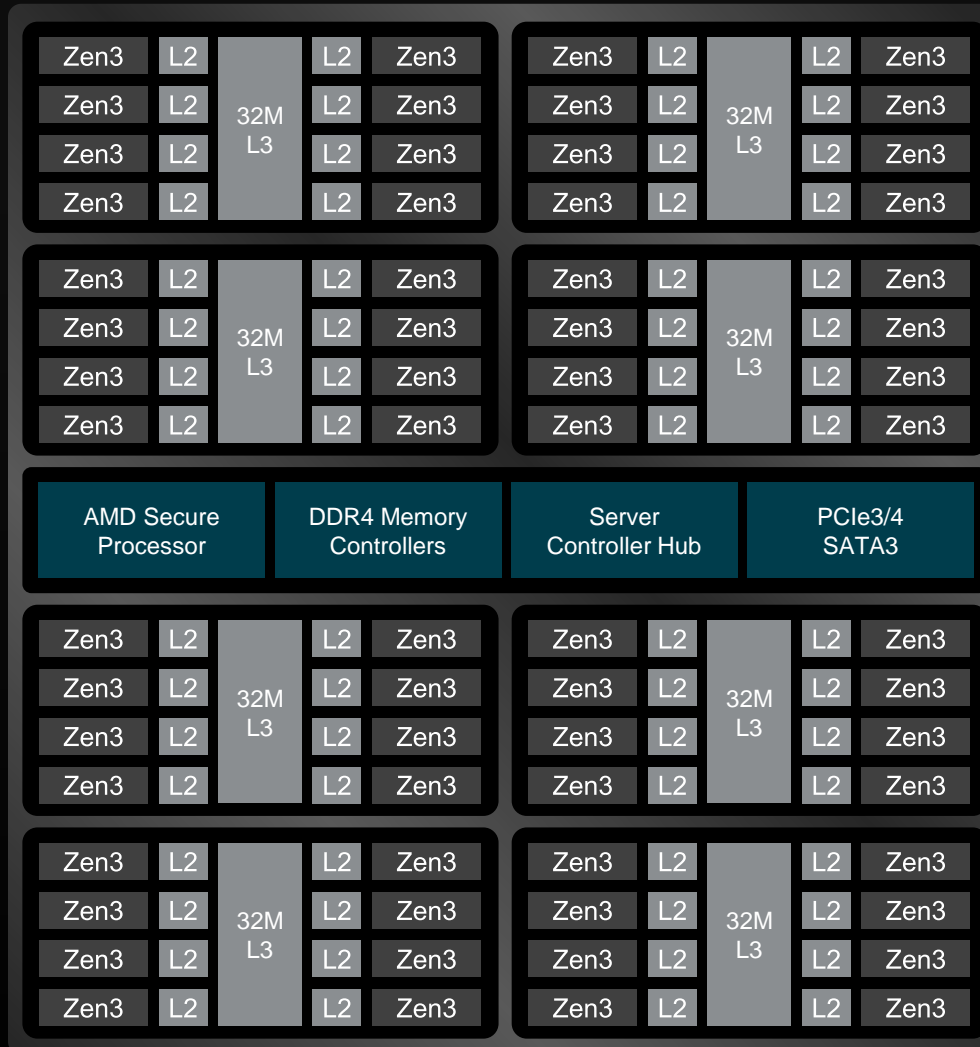
MEMORY

8 channel DDR4 with ECC up to 3200 MHz

Option for 4 or 6 channel Memory Interleaving¹

RDIMM, LRDIMM, 3DS, NVDIMM-N

2 DIMMs/channel capacity of 4TB/socket (256GB DIMMs)



PERFORMANCE

+Increased Performance/Socket, performance/core, single threaded performance, performance/core/watt²

Infinity Fabric™ Gen 2 (xGMI-2)

INTEGRATED I/O – NO CHIPSET

128 lanes PCIe® Gen3/4

- Used for PCIe, SATA, and Coherent Interconnect
- Up to 32 SATA or NVMe™ direct connect devices
- 162 lane option (2P config)

Server Controller Hub (USB, UART, SPI, LPC, I2C, etc.)

SECURITY FEATURES

Dedicated Security Subsystem

Secure Boot, Hardware Root-of-Trust

SME (Secure Memory Encryption)

SEV-ES (Secure Encrypted Virtualization & Register Encryption)

SEV-SNP (Secure Nested Paging)

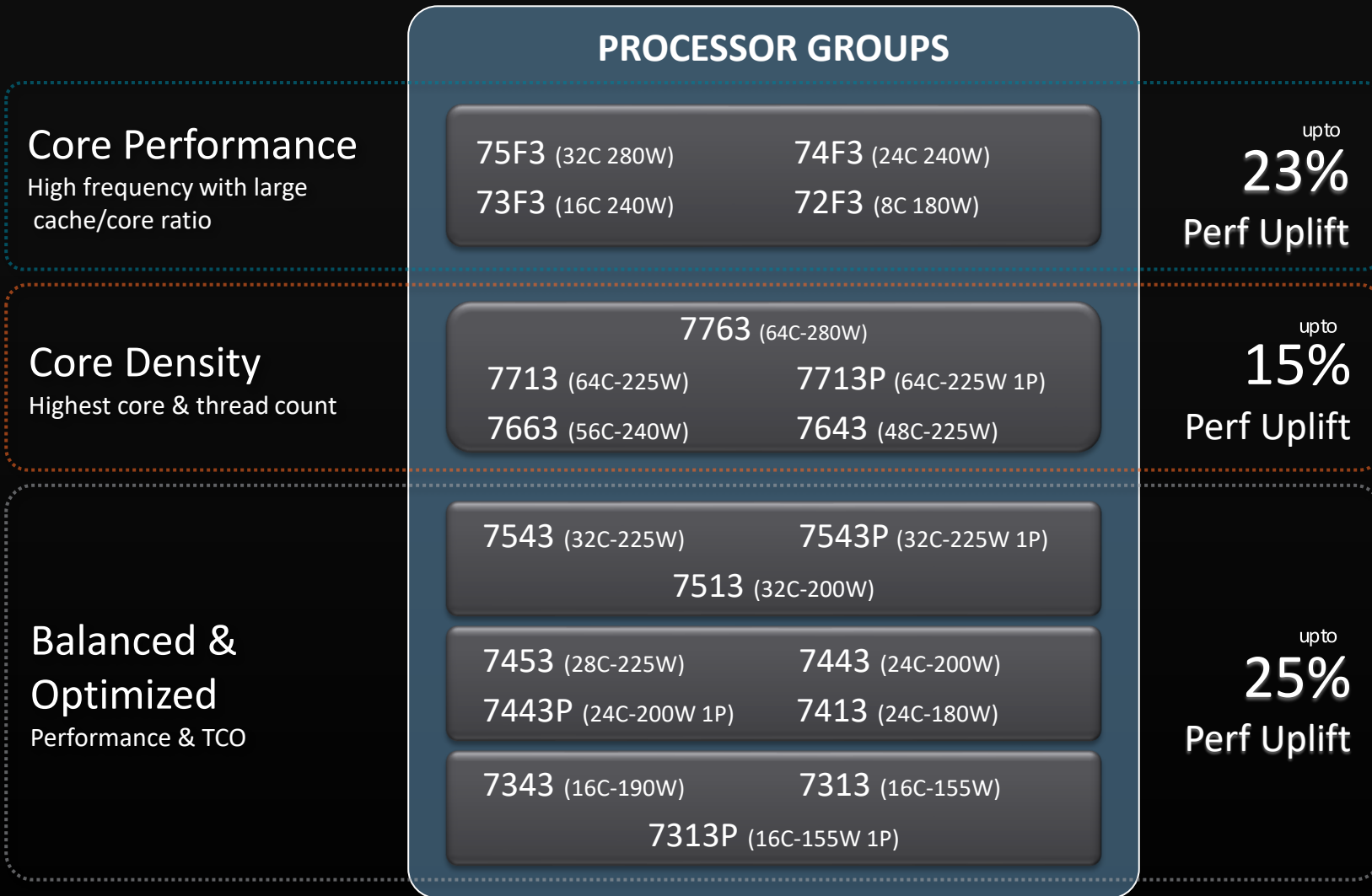
AMD EPYC™ - 7001, 7002, & "MILAN" COMPARISON

Category	7001	7002	MILAN
Socket		SP3	
Core	"Zen"	"Zen2"	"Zen3"
Process	14nm	7nm	7nm
Max Core Count/Threads	Up to 32C (64T)	Up to 64C (128T)	Up to 64C (128T)
Max L3 cache size	64MB	256MB	256MB
Max L3 cache per core	8MB	16MB	32MB
Memory Enhancements	8 ch DDR4-2666	8 ch DDR4-3200, NVDIMM-N	8 ch DDR4-3200, NVDIMM-N with DDR4 coupled DDR3200 and 6 channel memory interleave
PCIe® Enhancements	PCIe Gen3, 128L/Socket	PCIe Gen4, 128L/Socket	PCIe Gen4, 128L/Socket with IOMMU for improved IO performance
Security Enhancements	SME, SEV	SME, SEV-ES	SME, SEV-ES, SEV-SNP
New features	---	RDPRU, QOS enhancements, x2APIC extensions, UMIP	Hotplug surprise remove, Probe filter improvement
Chipset	NA	NA	NA
Power	120W - 180W	120W - 280W	120W - 280W

AMD EPYC™ 7003 ROADMAP CPU STACK

AMD EPYC™ 7003 Series Processor Models and Details							
Model #	Cores / Threads	Base Freq (GHz)	Max Boost Freq ⁸ (GHz)	Default TDP (W)	cTDP (W)	L3 Cache (MB)	2P/1P
7763	64 / 128	2.45	3.50	280W	225-280W	256	2P or 1P
7713	64 / 128	2.00	3.675	225W	225-240W	256	2P or 1P
7713P							1P Only
7663	56 / 112	2.00	3.50	240W	225-240W	256	2P or 1P
7643	48 / 96	2.30	3.60	225W	225-240W	256	2P or 1P
75F3	32 / 64	2.95	4.00	280W	225-280W	256	2P or 1P
7543	32 / 64	2.80	3.70	225W	225-240W	256	2P or 1P
7543P							1P Only
7513	32 / 64	2.60	3.65	200W	165-200W	128	2P or 1P
74F3	24 / 48	3.20	4.00	240W	225-240W	256	2P or 1P
7453	28 / 56	2.75	3.45	225W	225-240W	64	2P or 1P
7443	24 / 48	2.85	4.00	200W	165-200W	128	2P or 1P
7443P							1P Only
7413	24 / 48	2.65	3.60	180W	165-200W	128	2P or 1P
73F3	16/ 32	3.50	4.00	240W	225-240W	256	2P or 1P
7343	16 / 32	3.20	3.90	190W	165-200W	128	2P or 1P
7313	16 / 32	3.00	3.70	155W	155-180W	128	2P or 1P
7313P							1P Only
72F3	8 / 16	3.70	4.10	180W	165-200W	256	2P or 1P

EPYC™ 7003 CPU POSITIONING



Perf Uplift based on AMD EPYC 7002 processor projected SPECrate@2017_int_base performance scores are developed using computer modeling of each processors rev B0 which was then adjusted for the individual targeted frequency as of July 3, 2019. AMD EPYC 7003 scores are estimates base on EthanolIX platforms, See endnotes – Note 9. SPEC®, SPECrate® and SPEC CPU® are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information.



AMD EPYC™ SECURITY FEATURES

Secure Root-of-Trust
Technology

Secure Encrypted
Virtualization

Secure
Memory Encryption (SME)

Differences between generations

AMD EPYC™ Processors

Feature	Notes	“Zen”	“Zen2”	“Zen3”
SME	Secure memory encryption	✓	✓	✓
SEV	Encrypted memory support with 15 encrypted guests	✓	✓	✓
	Encrypted memory support 8TB/16TB PA space with 509/253 encrypted guests		✓	✓
SEV-ES	Encrypted VMCB state	✓	✓	✓
SEV-SNP	Secure Nested Paging			✓
GMET	Guest mode execute trap. Hypervisor can disallow supervisor execute of guest pages via VMCB		✓	✓
Shadow Stack	Shadow stack for protection against ROP attacks			✓
IBC	Indirect Branch Control	✓	✓	✓
UMIP	User Mode Instruction Prevention		✓	✓

PERFORMANCE TUNING GUIDE & ANDER RESSOURCEN

[DEVELOPER.AMD.COM/EPYC-TUNING-GUIDES](https://developer.amd.com/epyc-tuning-guides)

OS Tuning Guides

- Microsoft Windows® Tuning Guide for AMD EPYC™ 7002 Series Processors
- VMware® vSphere Tuning Guide for AMD EPYC™ 7002 Series Processors
- Optimizing Linux for AMD EPYC™ 7002 Series Processors with SUSE Linux Enterprise 15 SP1

Network Tuning Guides

- Linux® Network Tuning Guide for AMD EPYC™ 7002 Series Processor Based Servers
- Windows® Network Tuning Guide for AMD EPYC™ 7002 Series Processor Based Servers
- VMware® Network Tuning Guide for AMD EPYC™ 7002 Series Processor Based Servers

Workload Tuning Guides

- Workload Tuning Guide for AMD EPYC™ 7002 Series Processor Based Servers
- VMware® vSAN Tuning Guide for AMD EPYC™ 7002 Series Processors
- Database Tuning on Linux® OS: Reference Guide for AMD EPYC™ 7002 Series Processors

AMD Technical Document Library

SW Solution briefs

amd.com/en/processors/server-tech-docs/search

AMD Online Tools

Processor Selector Tool & Virtualized environment TCO calculator

amd.com/en/processors/epyc-tools

AMD Meet The Experts Webinars

amd.com/en/partner/meet-experts-webinars

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AMD Arena

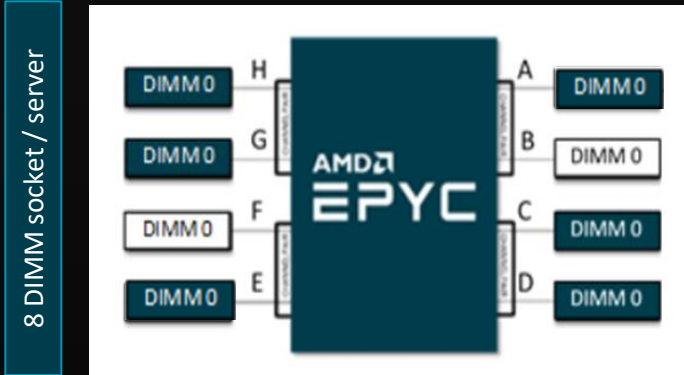
Incentivized partner training
Learn, earn, win!

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6 CHANNEL MEMORY INTERLEAVING MEMORY POPULATION RULES

1 DIMM Per Channel (DPC) Servers

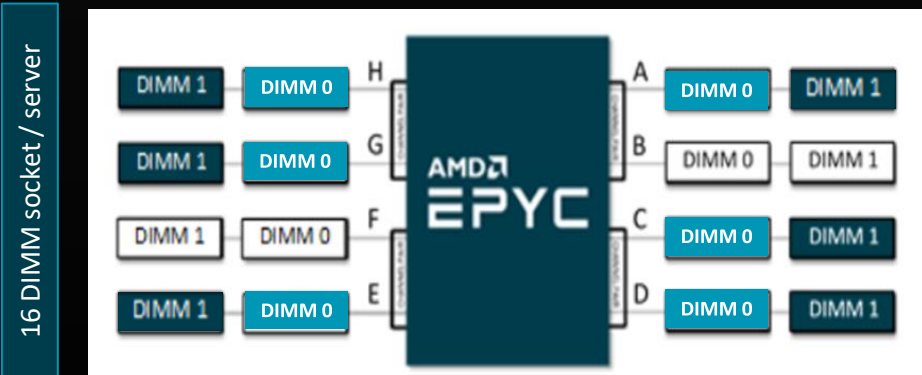


Supported by all EPYC™ 7003 CPUs

BENEFITS

- Help reduce overall memory cost
- Provide efficient memory balance for mid and low core count CPUs
- Can improve Perf / TCO due to lower memory costs
- Can deliver 3200 MHz memory speeds w/ 3200 MHz DIMMs in 1 DIMM per channel (DPC) configs.
- Supports up to 256GB of memory per channel for these configs. This could be 1DPC or 2DPC using these channels.
- Optimized to avoid memory hot-spotting when using the indicated channels.

Servers with 1 or 2 DIMMS Per Channel



- DIMM Empty DIMM slot
- DIMM Populated DIMM slot, 1 DPC
- DIMM 2 DPC populated configuration *

* DIMM type and size rules apply to these population types. Check with OEM for memory population rules.

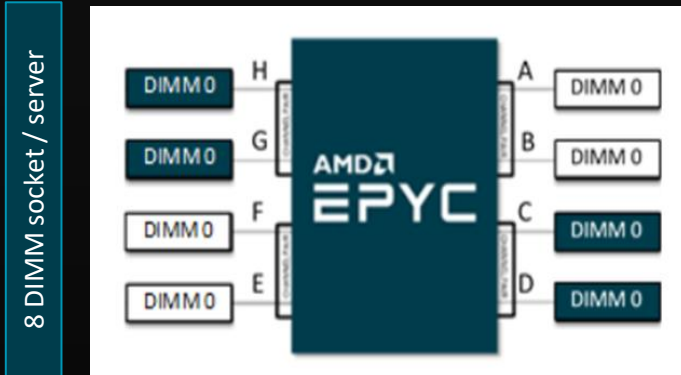
For optimum performance, the same size and type DIMMs should be used in all populated slots.



4 CHANNEL MEMORY INTERLEAVING

MEMORY POPULATION RULES - CPUS WITH 128MB OF L3 CACHE OR LESS

1 DIMM Per Channel (DPC) Servers

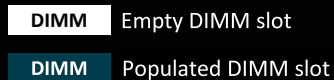
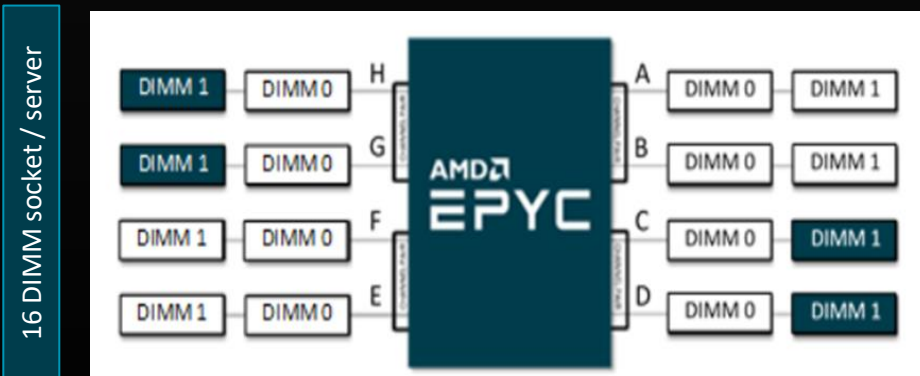


Supported by all EPYC™ 7003 CPUs w/ 128MB L3 cache or less

BENEFITS

- Help reduce overall memory cost
- Provide efficient memory balance for low core count CPUs
- Can improve Perf / TCO with fewer DIMMs
- Can deliver 3200 MHz memory speeds w/ 3200 MHz DIMMs in 1 DIMM per channel (DPC) configs.
- Avoids memory channel hot-spotting when using the recommended channels
- Help optimize low core count CPUs with lower memory costs for many workloads

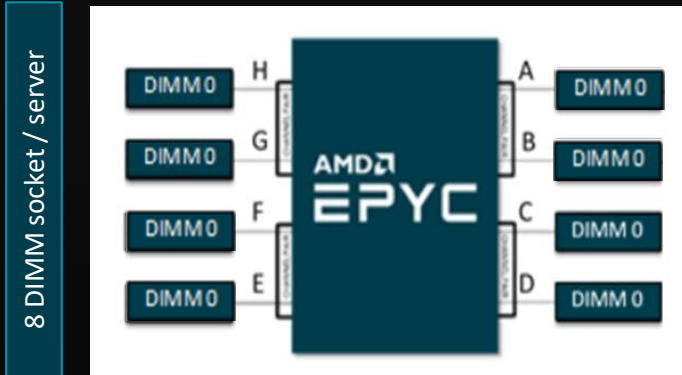
1 DIMM Per Channel (DPC) Servers



8 CHANNEL MEMORY INTERLEAVING

MEMORY POPULATION RULES

1 DIMM Per Channel (DPC) Servers

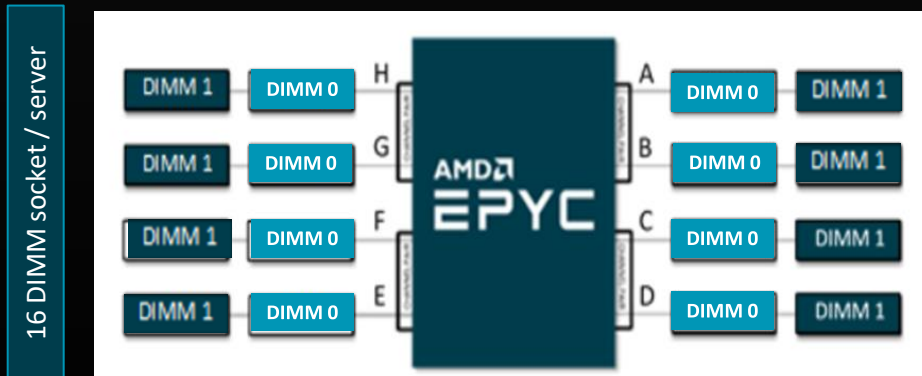


Supported by all EPYC™ 7003 CPUs

BENEFITS

- Help achieve a least cost / max memory performance solution
- Can deliver 3200 MHz memory speeds w/ 3200 MHz DIMMs in 1 DIMM per channel (DPC) configs.
- Enables maximum system memory bandwidth
- Help optimize core count with memory capacity and bandwidth for demanding workloads

Servers with 1 or 2 DIMMS Per Channel











- Empty DIMM slot
- Populated DIMM slot, 1 DPC
- 2 DPC populated configuration *

* DIMM type and size rules apply to these population types. Check with OEM for memory population rules.

For optimum performance, the same size and type DIMMs should be used in all populated slots.



SP3 "MILAN" TARGETED OPERATING SYSTEMS & HYPERVISORS

	N - 1	Launch (N)
 Microsoft	Server 2016	Server 2019 Azure Stack HCI v1
 vmware®	vSphere 6.7u3 P03	vSphere 7.0u1
 redhat.	see notes	RHEL 8.3
 SUSE	SLES 12 SP5 Requires maintenance update (Mar 4, 2020 Kernel 4.12.14-122.17)	SLES 15 SP2
 CANONICAL	Ubuntu 18.04.5	Ubuntu 20.04
 CITRIX®		Hypervisor 8.2
 CentOS		8.3
 ORACLE®	UEK 5.5	UEK 6.1

Windows note:

- X2APIC/256T not supported in 2016
- Sept 2019 Media Refresh & beyond provides full 256T/x2APIC support

RedHat notes:

- RHEL 7.x is in maintenance mode – not taking new features, therefore will not support Milan
- Milan users will need to upgrade to RHEL 8.3 (Nov 2020)
- RHEL uses a whitelist to check for known hardware configurations. RHEL versions that work for Rome are expected to boot and run, but the end-user will see the message “Unsupported Hardware Detected”.

ENDNOTES



EPYC-18: Max boost for AMD EPYC processors is the maximum frequency achievable by any single core on the processor under normal operating conditions for server systems. EPYC-18

MIL-001: AMD EPYC™ 7003 Series processors require a BIOS update from your server or motherboard manufacturer if used with a motherboard designed for the AMD EPYC™ 7002 Series processors. A motherboard designed at minimum for EPYC 7002 processors is required for EPYC 7003 Series processors. MIL-001

NOTE 1 - AMD EPYC 3rd Generation ("Milan") processor estimates are based on pre-production silicon on AMD Ethanol X reference platform, Ubuntu 20.04, latest AGESA (92RC2), 4 xGMI @ 10.7GT, with 1 DPC DDR3200 (32GBx16), AOCC3.0 (beta v04) compiler, in NPS4 mode, performance determinism, measured at AMD labs in Oct 2020. The actual numbers measured by our Boston ITs on actual production processors may vary based on platforms, hardware and software configurations and versions. SPEC®, SPECrate® and SPEC CPU® are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information.



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